

AMENDMENTS TO THE CLAIMS:

Please cancelled Claims 41-52 without prejudice or disclaimer.

Please amend Claims 22, and 28-30 as follows:

1 - 21. (Cancelled)

22. (Currently Amended) A pod ~~attachable~~ attached to an outside surface of a grounded electromagnetic-shielded chamber, ~~the chamber~~ having a door and a grounded flange portion~~[[,]]~~ around the door~~[[,]]~~ on the outside surface and containing a micro-device manufacturing apparatus, said pod comprising:

walls ~~configured to contain the~~ containing a substrate ~~and having an opening~~; and

a lid ~~configured to openably close the~~ for an opening defined by said walls, [[a]] the substrate being transferred between said pod and the grounded electromagnetic shielded chamber through the opening with said lid in an open state,

wherein said walls comprise an electromagnetic shield member, said electromagnetic shield member including a flange portion ~~configured to contact~~ contacting the grounded flange portion of the grounded electromagnetic shielded chamber without any intervening elements therebetween while said pod is attached to the outside surface.

23. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in front of said pod.

24. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in a bottom of said pod.

25. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises wire mesh arranged on or within said walls.

26. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises metal coatings arranged on said walls.

27. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises electromagnetic-shield materials arranged in said walls.

28. (Currently Amended) A micro-device manufacturing apparatus comprising:  
an electromagnetic-shielded chamber, ~~said chamber having a door and a flange~~  
~~portion around said door on an outside surface of said chamber;~~

a substrate transfer unit ~~arranged~~ placed in said electromagnetic shielded chamber;  
~~and configured to transfer the a substrate between said chamber and, a pod, the pod being~~  
~~attached to the~~ an outside surface of said electromagnetic shielded chamber including a substrate  
handling unit and having an electromagnetic shield member which includes a flange portion  
~~configured to in contact with said flange portion of said chamber the outside surface;~~ and

a processing unit ~~placed~~ arranged in said electromagnetic shielded chamber, ~~and~~  
configured to process the substrate transferred into said chamber from the pod by said transfer  
unit ~~and comprising a wafer chuck for the substrate to be processed,~~

wherein said ~~flange portion of said~~ electromagnetic shielded chamber is  
~~grounded and configured to contact the~~ has a door and a grounded flange portion of the pod  
which surrounds said door on the outside surface of said electromagnetic shielded chamber, is  
connected to ground, and is in contact with the flange portion of the pod without any intervening  
elements therebetween while the pod is attached to the outside surface.

29. (Currently Amended) An apparatus according to 28, wherein said substrate  
transfer unit ~~is configured to transfer~~ transfers the substrate between said chamber and the pod  
~~through~~ with said door in an open state.

30. (Currently Amended) An apparatus according to 28, wherein said processing  
unit ~~is configured to expose the~~ exposes the substrate to a pattern.

31. (Previously Presented) An apparatus according to Claim 28, wherein a lid of the  
pod is arranged in front of the pod.

32. (Previously Presented) An apparatus according to Claim 28, wherein a lid of the  
pod is arranged in a bottom of the pod.

33. (Previously Presented) An apparatus according to Claim 28, wherein walls of the pod comprises the electromagnetic shield member.

34 - 52. (Cancelled)